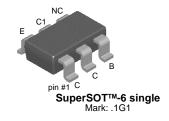


# FMBSA06

### **NPN General Purpose Amplifier**

- This device is designed for general purpose amplifier applications at collector currents to 300 mA.
- · Sourced from Process 12.



# **Absolute Maximum Ratings\*** T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Value	Units
V <sub>CEO</sub>	Collector-Emitter Voltage	80	V
$V_{CBO}$	Collector-Base Voltage	80	V
V <sub>EBO</sub>	Emitter-Base Voltage	4.0	V
I <sub>C</sub>	Collector Current - Continuous	500	mA
T <sub>J</sub> , T <sub>STG</sub>	Operating and Storage Junction Temperature Range	- 55 ~ 150	°C

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

- These ratings are based on a maximum junction temperature of 150 degrees C.
  These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

### Electrical Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Test Condition	Min.	Max.	Units
Off Characte	eristics				•
V <sub>(BR)CEO</sub>	Collector-Emitter Sustaining Voltage *	$I_C = 1.0 \text{mA}, I_B = 0$	80		V
V <sub>(BR)EBO</sub>	Emitter-Base Breakdown Voltage	$I_E = 100 \mu A, I_C = 0$	4.0		V
CEO	Collector Cut-off Current	$V_{CE} = 60V, I_{B} = 0$		0.1	μΑ
СВО	Collector Cut-off Current	$V_{CB} = 80V, I_{E} = 0$		0.1	μΑ
On Characte	eristics				•
h <sub>FE</sub>	DC Current Gain	I <sub>C</sub> = 10mA, V <sub>CE</sub> = 1.0V	100		
		$I_C = 100 \text{mA}, V_{CE} = 1.0 \text{V}$	100		
√ <sub>CE(sat)</sub>	Collector-Emitter Saturation Voltage	$I_C = 100 \text{mA}, I_B = 10 \text{mA}$		0.25	V
V <sub>BE(on)</sub>	Base-Emitter On Voltage	$I_C = 10 \text{mA}, V_{CE} = 1.0 \text{V}$		1.2	V
	I Characteristics				
f <sub>T</sub>	Current Gain Bandwidth Product	$I_C = 10$ mA, $V_{CE} = 2.0$ V, $f = 100$ MHz	100		MHz
Pulse Test: Pulse	Width ≤ 300μs, Duty Cycle ≤ 2.0%	•			

### Thermal Characteristics T<sub>a</sub>=25°C unless otherwise noted

Symbol	Parameter	Max.	Units
$P_{D}$	Total Device Dissipation *	700	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, total	180	°C/W

<sup>\*</sup> Device mounted on a 1 in 2 pad of 2 oz copper.

# **Typical Characteristics**

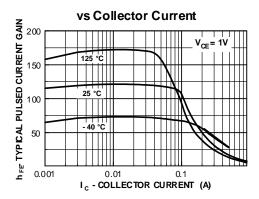


Figure 1. Typical Pulsed Current Gain vs Collector Current

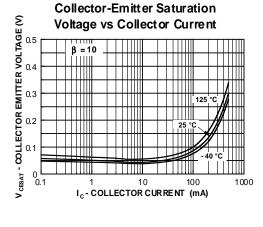


Figure 2. Collector-Emitter Saturation Voltage vs Collector Current

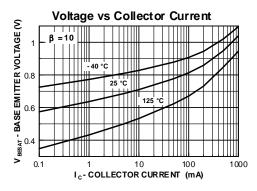


Figure 3. Base-Emitter Saturation Voltage vs Collector Current

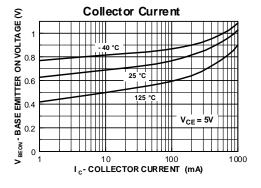


Figure 4. Base-Emitter On Voltage vs Collector Current

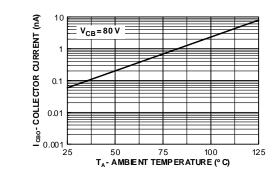


Figure 5. Collector Cutoff Current vs Ambient Temperature

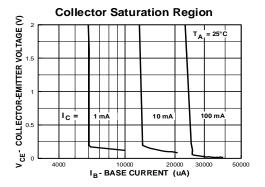


Figure 6. Collector Saturation Region

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# Typical Characteristics (Continued)

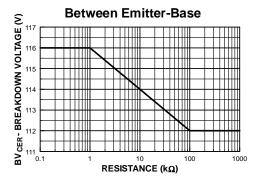


Figure 7. Collector-Emitter Breakdown Voltage with Resistance Between Emitter-Base

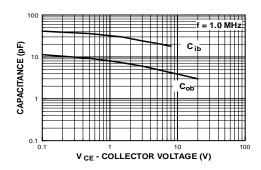


Figure 8. Input and Output Capacitance vs Reverse Voltage

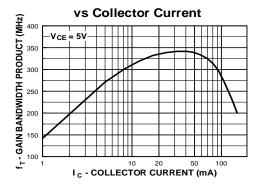
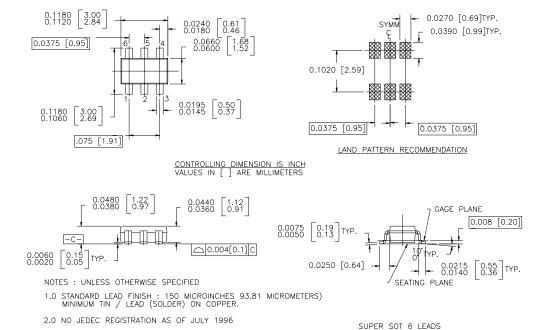


Figure 9. Gain Bandwidth Product vs Collector Current

# **Package Dimensions**

# SuperSOT™-6



Dimensions in Millimeters

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EcoSPARK™	HiSeC™	MSX™	QT Optoelectronics™	TinyLogic <sup>®</sup>
E <sup>2</sup> CMOS™	$I^2C^{TM}$	MSXPro™	Quiet Series™	TINYOPTO™
EnSigna™	i-Lo™	OCX™	RapidConfigure™	TruTranslation™
FACT™	ImpliedDisconnect™	OCXPro™	RapidConnect™	UHC™
FACT Quiet Series™		OPTOLOGIC <sup>®</sup>	μSerDes™	UltraFET <sup>®</sup>
Across the board. Around the world.™		OPTOPLANAR™	SILENT SWITCHER®	VCX <sup>TM</sup>
The Power Franchise®		PACMAN™	SMART START™	
Programmable Active Droop™		POP™	SPM™	

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No Identification Needed	Full Production	This datasheet contains final specifications. Fairchild Semiconductor reserves the right to make changes at any time without notice in order to improve design.
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